



PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-026910

(43)Date of publication of application : 29.01.1999

(51)Int.Cl.

H05K 1/18

(21)Application number : 09-178000 (71)Applicant : DENSO CORP
(22)Date of filing : 03.07.1997 (72)Inventor : NIIMI HIROSHI

(54) STRUCTURE FOR SOLDERING ELECTRONIC PART

(57)Abstract:

PROBLEM TO BE SOLVED: To improve reliability of a soldered part by releasing a stress.

SOLUTION: In an electronic part 2 mounted on a surface of a printed board 1, an electrode 2b is pulled out on the surface of a ceramic board 2a of a mother board. Also, an insulator part 3 is integrally provided on the surface of the printed board 1 side in the ceramic board 2a. This insulator 3 is provided so as to be projected from the surface of an electrode 2b faced to a wiring pattern 1b of the printed board 1 only by prescribed dimension 50-100 μ m. This electronic part 2 is arranged at the prescribed position of the surface of the printed board 1, while the face on which the insulator part 3 is formed is faced to the print board 1 side, and this electronic part 2 is soldered in a state that a clearance equivalent to the height of the insulator part 3 is secured between a wiring pattern 1b of the print board 1 and the electrode 2b of the electronic part 2 by the insulator part 3.

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]
[Patent number]
[Date of registration]
[Number of appeal against examiner's
decision of rejection]
[Date of requesting appeal against
examiner's decision of rejection]
[Date of extinction of right]

Copyright (C); 1998,2000 Japanese Patent Office